Lin Zone Ching

List of Publications by Year
in descending order

45	406	933447	839539
papers	citations	10	18
		h-index	g-index

46	46	46	286
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Multiple linear regression analysis of the overlay accuracy model. IEEE Transactions on Semiconductor Manufacturing, 1999, 12, 229-237.	1.7	43
2	3D nano-scale cutting model for nickel material. Journal of Materials Processing Technology, 2007, 192-193, 27-36.	6.3	34
3	The building of spindle thermal displacement model of high speed machine center. International Journal of Advanced Manufacturing Technology, 2007, 34, 556-566.	3.0	30
4	The study of ultra-precision machining and residual stress for NiP alloy with different cutting speeds and depth of cut. Journal of Materials Processing Technology, 2000, 97, 200-210.	6.3	29
5	A study of the estimation method of the cutting force for a conical tool under nanoscale depth of cut by molecular dynamics. Nanotechnology, 2008, 19, 115701.	2.6	29
6	A study of material removal amount of sapphire wafer in application of chemical mechanical polishing with different polishing pads. Journal of Mechanical Science and Technology, 2012, 26, 2353-2364.	1.5	27
7	A study of oblique cutting for different low cutting speeds. Journal of Materials Processing Technology, 2001, 115, 313-325.	6.3	23
8	Measurement point prediction of flatness geometric tolerance by using grey theory. Precision Engineering, 2001, 25, 171-184.	3.4	18
9	Abrasive removal depth for polishing a sapphire wafer by a cross-patterned polishing pad with different abrasive particle sizes. International Journal of Advanced Manufacturing Technology, 2014, 74, 25-36.	3.0	14
10	Simulation of temperature field during nanoscale orthogonal cutting of single-crystal silicon by molecular statics method. Computational Materials Science, 2014, 81, 58-67.	3.0	14
11	Establishment of a cutting force model and study of the stressâ€“strain distribution in nano-scale copper material orthogonal cutting. International Journal of Advanced Manufacturing Technology, 2007, 33, 425-435.	3.0	12
12	A study of estimating cutting depth for multi-pass nanoscale cutting by using atomic force microscopy. Applied Surface Science, 2012, 258, 4513-4522.	6.1	10
13	Analysis of point fabrication model for nearâ€field photolithography with experimental study. Scanning, 2006, 28, 32-41.	1.5	9
14	Thermal conductivity investigation for upsetting with a procedure of combining inverse model and the proposed regularization of Tikhonov method. Journal of Materials Processing Technology, 2005, 167, 208-217.	6.3	8
15	The near-field power density distribution characteristics for different types of optical fiber probes. International Journal of Advanced Manufacturing Technology, 2005, 26, 1289-1297.	3.0	8
16	Inverse calculation of the friction coefficient for upsetting a cylindrical mild steel by the experimental load. Journal of Materials Processing Technology, 2006, 178, 297-306.	6.3	8
17	Combination of improved cosine similarity and patent attribution probability method to judge the attribution of related patents of hydrolysis substrate fabrication process. Advanced Engineering Informatics, 2016, 30, 26-38.	8.0	8
18	A study of patent analysis of LED bicycle light by using modified DEMATEL and life span. Advanced Engineering Informatics, 2017, 34, 136-151.	8.0	8

#	Article	IF	Citations
19	Establishing a theoretical model for abrasive removal depth of silicon wafer chemical mechanical polishing by integrating a polishing times analytical model and specific down force energy theory. International Journal of Advanced Manufacturing Technology, 2018, 95, 4671-4683.	3.0	7
20	Application of the grey system in the planning of the measuring points under the range of the dimensional tolerance of a plane workpiece. International Journal of Computer Integrated Manufacturing, 2000, 13, 555-566.	4.6	6
21	Performance of coated tungsten carbide tools on milling printed circuit board. Journal of Materials Processing Technology, 2009, 209, 303-309.	6.3	6
22	3-D finite element simulation of wafer thermal distortion and stress fields in exposure process. International Journal of Heat and Mass Transfer, 2002, 45, 619-630.	4.8	5
23	Tool wear investigation on the precision progressive die for the IC dam-bar cutting process. International Journal of Advanced Manufacturing Technology, 2003, 22, 344-356.	3.0	5
24	The application of the moment equilibrium model to the offset of pressure center of trimming progressive die in IC packaging machine. Journal of Materials Processing Technology, 2003, 140, 653-661.	6.3	5
25	Distribution of polishing times for a wafer with different patterned polishing pads during CMP and CCMP. Surface and Coatings Technology, 2010, 204, 3101-3107.	4.8	5
26	Temperature field analysis of IC molding process based on three dimensional finite element model. Heat and Mass Transfer, 2004, 40, 477.	2.1	4
27	Friction coefficient of upsetting with a procedure of combining the inverse model and the Tikhonov method. International Journal of Mechanical Sciences, 2006, 48, 717-725.	6.7	4
28	A band-type network model for the time-series problem used for IC leadframe dam-bar shearing process. International Journal of Advanced Manufacturing Technology, 2009, 40, 1252-1266.	3.0	4
29	Error analysis and regression mode of the Vâ€grooved sample in the atomic force microscope simulation measurement mode by the molecular mechanics. Scanning, 2009, 31, 147-159.	1.5	4
30	A study of improving overlay accuracy for a stepper in IC manufacture. International Journal of Advanced Manufacturing Technology, 1998, 14, 835-847.	3.0	3
31	The fixture planning of modular fixtures for measurement. IIE Transactions, 2000, 32, 345-359.	2.1	3
32	A knowledge acquisition model for selecting coordinate measuring machines using inductive learning. IIE Transactions, 2000, 32, 573-583.	2.1	2
33	A neural network-based algorithm that searches for the measuring points of a rule surface. IIE Transactions, 2000, 32, 333-343.	2.1	2
34	Quality improvement by using grey prediction tool compensation model for uncoated and TiAlCN-coated tungsten carbide tools in depanel process of memory modules. International Journal of Advanced Manufacturing Technology, 2009, 40, 857-864.	3.0	2
35	Investigatory nanoscale thickness of the chemical reaction layer of sapphire substrate for the various dipping temperatures of slurry suitable in CMP. Journal of Materials Science: Materials in Electronics, 2017, 28, 13041-13052.	2.2	2
36	The fixture planning of modular fixtures for measurement. IIE Transactions, 2000, 32, 345-359.	2.1	1

#	Article	IF	Citations
37	Study of temperature distributions in wafer exposure process. Heat and Mass Transfer, 2002, 38, 639-648.	2.1	1
38	Inverse model of fiber probe aperture size using a nonâ€destructive method. Scanning, 2009, 31, 211-220.	1.5	1
39	An innovative method and experiment for fabricating bulgy shape nanochannel using AFM. Applied Surface Science, 2015, 347, 347-358.	6.1	1
40	A knowledge acquisition model for selecting coordinate measuring machines using inductive learning. IIE Transactions, 2000, 32, 573-583.	2.1	0
41	A neural network-based algorithm that searches for the measuring points of a rule surface. IIE Transactions, 2000, 32, 333-343.	2.1	0
42	Matrix-presentation linear least square error method of inverse elastic-plastic large deformation finite element model for upsetting. International Journal of Advanced Manufacturing Technology, 2006, 30, 45-53.	3.0	0
43	Analysis of simulated scanning of atomicâ€scale silicon surface by atomic force microscopy. Scanning, 2008, 30, 392-404.	1.5	0
44	Investigation of Damping Coefficient of Air Motor Rotation Experiment. Journal of System Design and Dynamics, 2008, 2, 996-1005.	0.3	0
45	Nano-Scale Simulative Measuring Model for Tapping Mode Atomic Force Microscopy and Analysis for Measuring a Nano-Scale Ladder-Shape Standard Sample. Journal of Nanoscience and Nanotechnology, 2010, 10, 4400-4410.	0.9	0